

# SOT1390-1

WLCSP12, wafer level chip scale package; 12 bumps; 0.4 mm pitch; 1.36 mm x 1.66 mm x 0.51 mm body (backside coating included)

11 September 2017

Package information

## 1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP12
Package type industry code	WLCSP12
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	9-9-2017
Manufacturer package code	SOT1390-1

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		1.63	-	1.66	1.69	mm
E	package width		1.33	-	1.36	1.39	mm
A	seated height		0.47	-	0.51	0.55	mm
A <sub>2</sub>	package height		0.29	-	0.31	0.34	mm
e	nominal pitch		-	-	0.4	-	mm
n <sub>2</sub>	actual quantity of termination		-	-	12	-	



2. Package outline

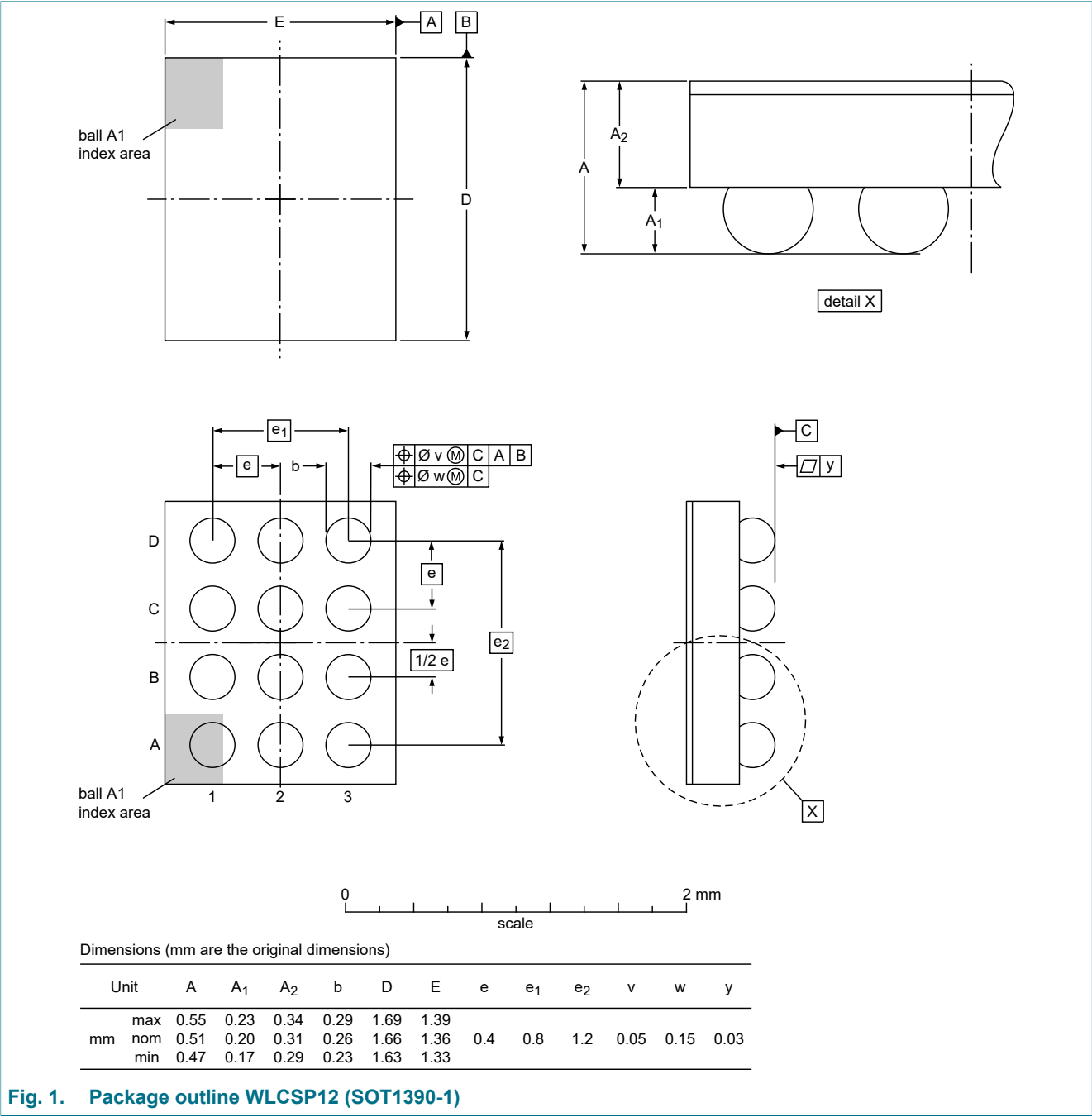


Fig. 1. Package outline WLCSP12 (SOT1390-1)

WLCSP12, wafer level chip scale package; 12 bumps; 0.4 mm pitch; 1.36 mm x 1.66 mm x 0.51 mm body  
(backside coating included)

### 3. Legal information

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